

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6654847

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YI-DA TSAI	08/27/2019
CHING-HUA HSIEH	08/27/2019
CHIH-WEI LIN	08/27/2019
TSAI-TSUNG TSAI	08/27/2019
SHENG-CHIEH YANG	03/27/2021
CHIA-MIN LIN	10/08/2019
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	30078
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16547579
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	083474-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	04/14/2021
Total Attachments: 5	

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DECLARATION AND ASSIGNMENT

FOR UTILITY OR DESIGN PATENT APPLICATION

Declaration Submitted With Initial Filing

OR

Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

SEMICONDUCTOR PACKAGE AND METHOD OF FORMING THE SAME

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

The attached application,

OR

United States Application Number or PCT International application number

16/547,579 Filed on 2019/8/22

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Taiwan Semiconductor Manufacturing Company, Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

P20181337US00
83474-US-PA

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Yi - Da Tsai Date: 2019/08/27

Legal Name of Sole or First Inventor: **Yi-Da Tsai**

Residence: Chiayi Country, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Ching - Hua Hsieh Date: 2019/08/27

Legal Name of Additional Joint Inventor, if any: **Ching-Hua Hsieh**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chih - Wei Lin Date: 2019/08/27

Legal Name of Additional Joint Inventor, if any: **Chih-Wei Lin**

Residence: Hsinchu County, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Tsai - Tsung Tsai Date: 2019/08/27

Legal Name of Additional Joint Inventor, if any: **Tsai-Tsung Tsai**

Residence: Taoyuan City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Sheng-Chieh Yang**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: _____ Date: _____

Legal Name of Sole or First Inventor: **Yi-Da Tsai**

Residence: Chiayi Country, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Ching-Hua Hsieh**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Chih-Wei Lin**

Residence: Hsinchu County, Taiwan

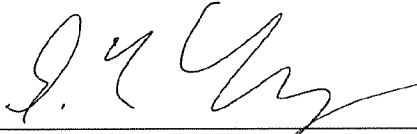
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Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Tsai-Tsung Tsai**

Residence: Taoyuan City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature:  _____ Date: 2021.03.29

Legal Name of Additional Joint Inventor, if any: **Sheng-Chieh Yang**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

P20181337US00
83474-US-PA

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Chia-Min Lin Date: 2019/10/08

Legal Name of Additional Joint Inventor, if any: Chia-Min Lin

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.